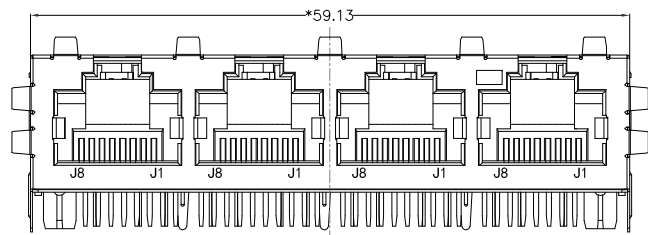
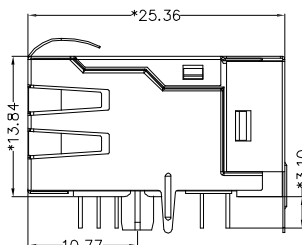


REACH & RoHS
COMPLIANT

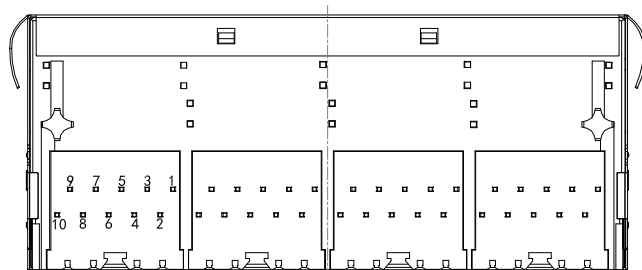
REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	GQ,Chen	2018.07.24



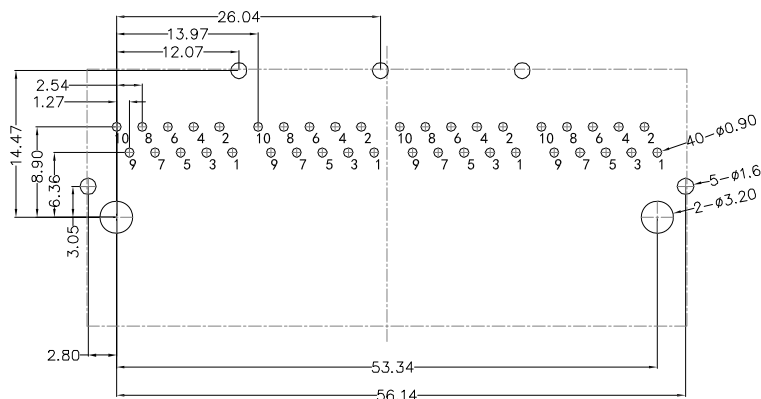
FRONT VIEW



RIGHT SIDE VIEW



BOTTOM VIEW



RECOMMENDED PCB LAYOUT
VIEWED FROM COMPONENT SIDE

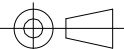
MATERIAL:

HOUSING: PA66,UL94V-0,BLACK.
 TERMINALS BRACKET: PA66,UL94V-0,BLACK.
 SHIELD: C2680,T=0.20MM,NICKEL PLATING ON ALL AREA.
 TERMINAL: PHOSPHOR BRONZE C5210,T=0.35MM,
 6U" GOLD PLATING ON CONTACT AREA.

MECHANICAL:

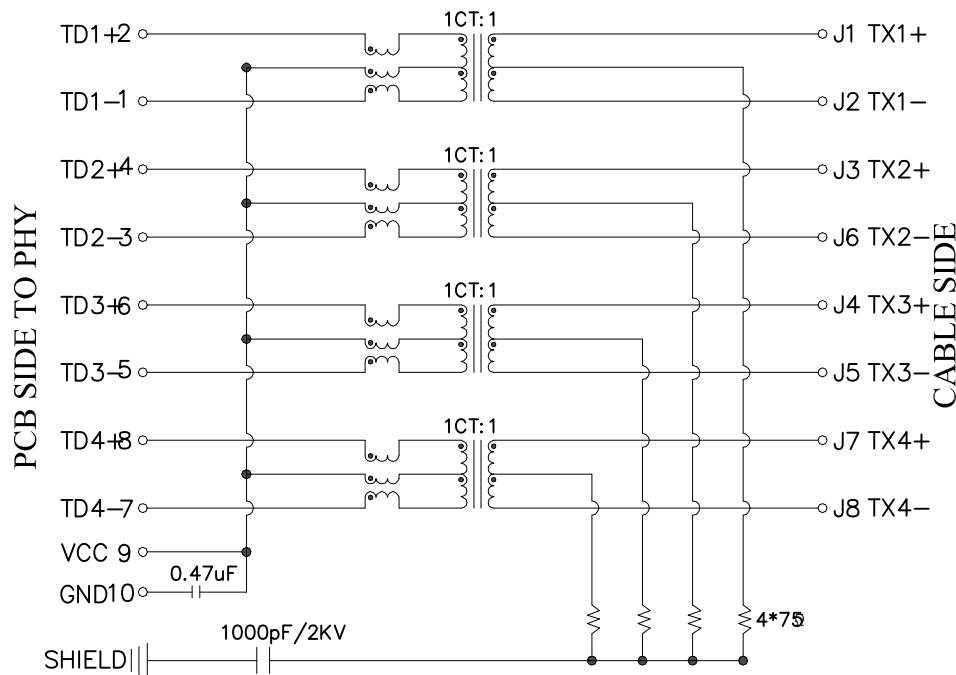
DURABILITY: 750 CYCLES MIN.
 MATING FORCE: 23N MAX.
 OPERATING TEMPERATURE: -40°C~+85°C.
 STORAGE TEMPERATURE: -40°C~+85°C.
 ALL CRITICAL DIMENSIONS WITH "*"

 东莞市涪程电子科技有限公司
 DONG GUAN FU CHENG ELECTRONIC TECHNOLOGY Co., LTD

TITLE: TAB-UP 1X4 1000BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
PART NO.: FCRJ45-314Q116HWA2D3057	SACLE 1:1	REV A0	x±0.35	x°±3.0°	CHECKED BY: TW.Xu
REMARK:	SHEET 1/1		.xx±0.25	.xx°±1.5°	DESIGND BY: GQ,Chen
			.xxx±0.10	.xxx°±1.0°	

REACH & RoHS
COMPLIANT

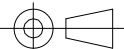
REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	GQ,Chen	2018.07.24



Electrical:

- Turn ratio: 2~1: J1~J2=1CT:1CT(±2%),
4~3: J3~J6=1CT:1CT(±2%),
6~5: J4~J5=1CT:1CT(±2%),
8~7: J7~J8=1CT:1CT(±2%).
- OCL: 350uH Min. at 100KHz 100mV 8mA DC.
- Insertion Loss: -1.0 dB Max 1~100MHz.
- Return loss: -20dB Min 1~10MHz;
-16dB Min 10~30MHz.
-12dB Min 30~60MHz.
-10dB Min 60~80MHz.
- Cross talk: -40dB Min 1~30MHz;
-35dB Min 30~60MHz;
-30dB Min 60~100MHz;
- CMR: -30dB Min 1~100MHz;
- Hi-Pot: 2250V DC 6S 1mA PRI TO SEC

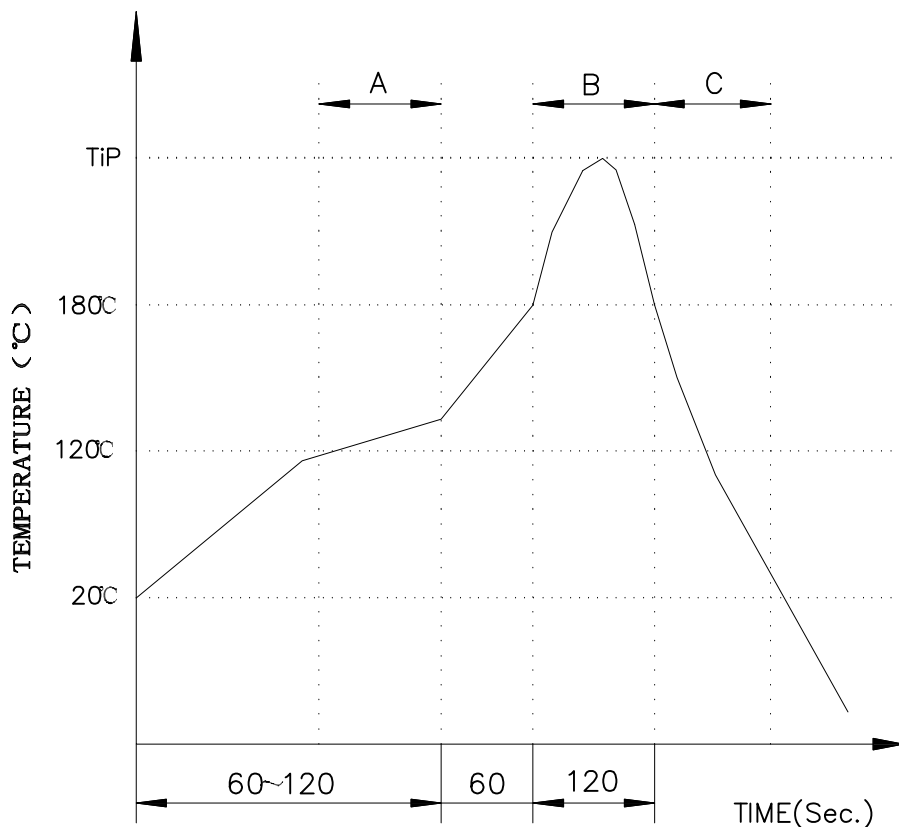
 东莞市浚程电子科技有限公司
DONG GUAN FU CHENG ELECTRONIC TECHNOLOGY Co., LTD

TITLE: TAB-UP 1X4 1000BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
PART NO.: FCRJ45-314Q116HWA2D3057	SACLE 1:1	REV A0	x±0.35	x°±3.0°	CHECKED BY: TW.Xu
REMARK:	SHEET 1/1		.xx±0.25	.xx°±1.5°	DESIGN BY: GQ,Chen
			.xxx±0.10	.xxx°±1.0°	

REACH & RoHS
COMPLIANT

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	GQ,Chen	2018.07.24

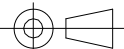
PROFILE OF WAVE SOLDER



A.Preheating B.Soldering C.Gradual Cooling
 Tip temperature:260±5°C.
 Tip temperature time:5Sec Max.
 Tip melting point of Sn96.5/Ag3/Cu0.5:217°C.

Remarks: after wave soldering, the plastic positioning columns of the product which under the PCB will be slightly melted, but it won't affect its function.

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PART NO.: FCRJ45-314Q116HWA2D3057	SACLE 1:1	REV A0	x±0.35	x°±3.0°	CHECKED BY: TW.Xu
REMARK:	SHEET 1/1		.xx±0.25	.xx°±1.5°	DESIGND BY: GQ,Chen
			.xxx±0.10	.xxx°±1.0°	